

20V P-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

Product Summary

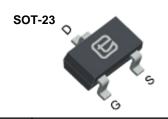
 $\rm V_{\rm DS}$ -20V I_D (at $V_{GS} = -4.5V$) -2.6A

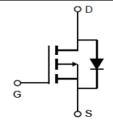
 $R_{DS(ON)}$ (at $V_{GS} = -10V$) < 68mΩ $R_{DS(ON)}$ (at $V_{GS} = -4.5V$)

 $R_{DS(ON)}$ (at $V_{GS} = -2.5V$) < 110mΩ



 $< 80 m\Omega$





Part Number	Package Type	Form	Marking
TTX2301A	SOT-23	Tape & Reel	2301A

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

3 ()				
Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	-20	V
Gate-Source Voltage		V _{GS}	±12	V
Continuous Drain Current B	T _C =25°C		-2.6	۸
	T _C =70°C	I _D	-2.1	А
Pulsed Drain Current ^A		I _{DM}	-7.8	Α
Avalanche Current A		I _{AS}	-12	Α
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	21.6	mJ
Power Dissipation ^C	T _C =25°C	P _D	0.89	W
	T _C =70°C		0.57	W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C
T		•		

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Lead	Steady-State	$R_{\Theta JL}$	120	00.444	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	140	°C/W	



Symbol	Parameter	Conditions		Value			Units
Зупьог	ool Parameter Conditions			Min	Тур	Max	Onits
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$		-20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V	T _J =25°C T _J =125°C			-1	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	1 _J =125°C			-100 ±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA		-0.45	-0.7	-0.95	V
		V _{GS} =-10V, I _D =-2.6A			54	68	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-2.6A			64	80	mΩ
		V _{GS} =-2.5V, I _D =-2.6A			83	110	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-2.6A			6		S
V _{SD}	Diode Forward Voltage	I _S =-2.6A, V _{GS} =0V				-1	V
I _s	Maximum Body-Diode Continuous Current B					-2.6	Α
DYNAMIC	PARAMETERS					•	
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, f =1MH _Z			493		
C _{oss}	Output Capacitance				56		pF
C _{rss}	Reverse Transfer Capacitance				51		
R_g	Gate Resistance	f =1MH _Z			5.2		Ω
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =-10V,V _{DS} =-10V, I _D =-2.6A			9.1		nC
Q _g (4.5V)	Total Gate Charge				4.2		
Q_{gs}	Gate Source Charge				0.9		
Q_{gd}	Gate Drain Charge				0.8		
t _{D(on)}	Turn-On Delay Time	V_{GS} =-4.5V, V_{DS} =-10V, I_{D} =-2.6A, R_{G} =2.5 Ω			3.2		
t _r	Turn-On Rise Time				2.4		ns
$t_{D(off)}$	Turn-Off Delay Time				17		
t _f	Turn-Off Fall Time				3.8		
t _{rr}	Body Diode Reverse Recovery Time		lue -		4.6		ns
Q _{rr}	Body Diode Reverse Recovery Charge	-I _F =-2.6A, di/dt =100A/μs			1.8		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

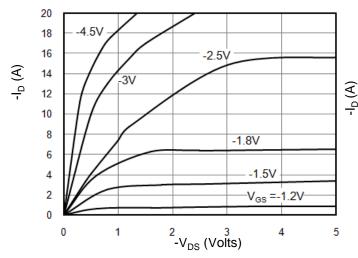


Figure 1: On-Region Characteristics

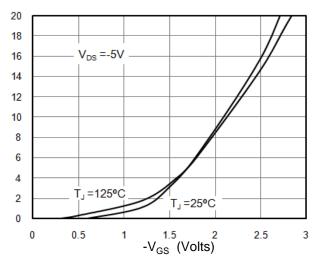


Figure 2: Transfer Characteristics

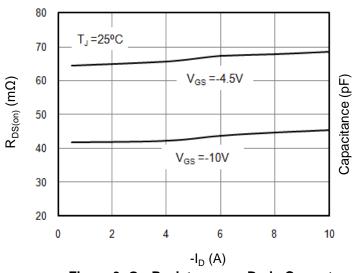


Figure 3: On-Resistance vs. Drain Current

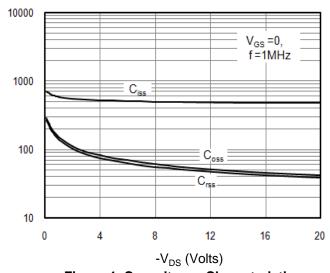


Figure 4: Capacitance Characteristics

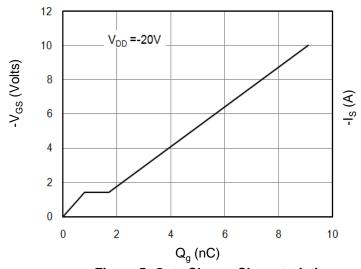


Figure 5: Gate Charge Characteristics

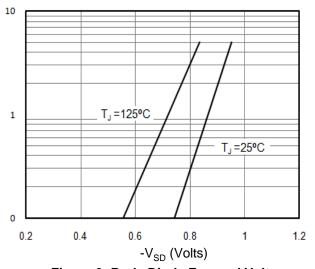


Figure 6: Body Diode Forward Voltage



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

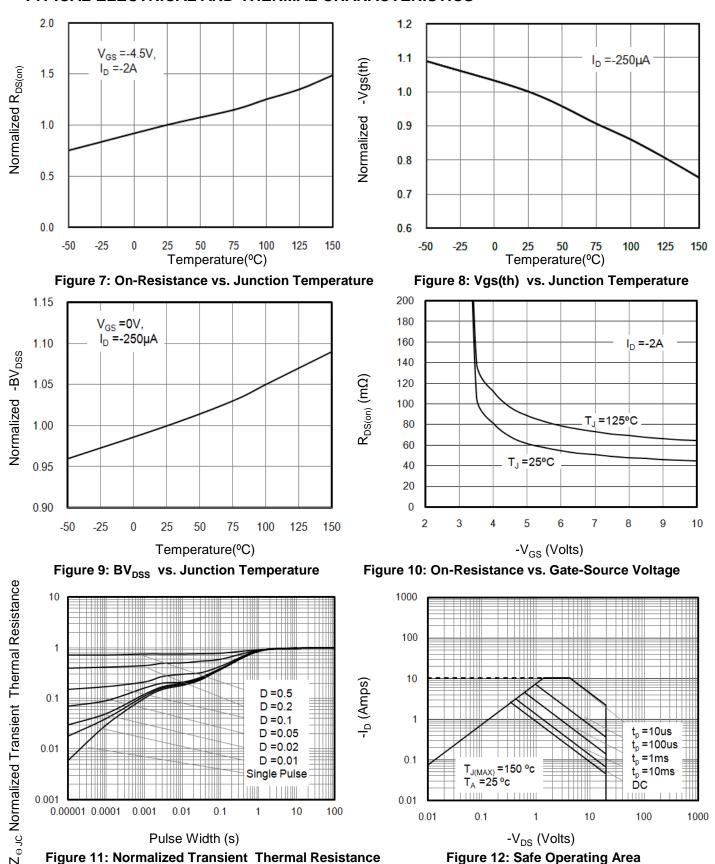


Figure A: Gate Charge Test Circuit and Waveform

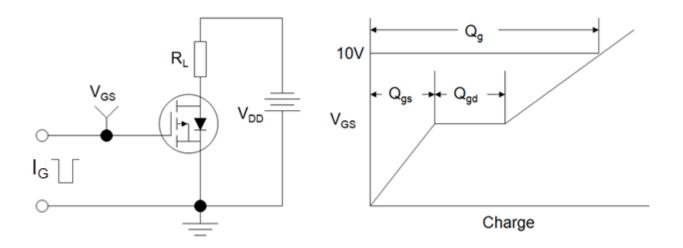


Figure B: Resistive Switching Test Circuit and Waveform

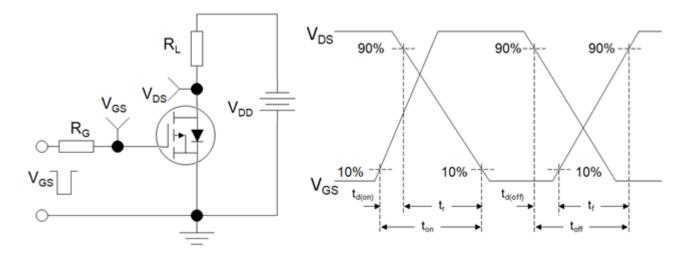
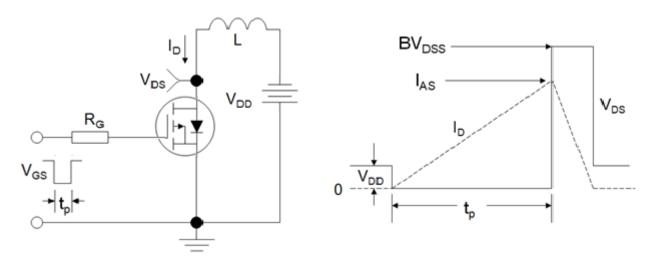
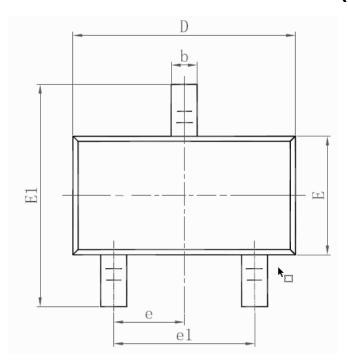


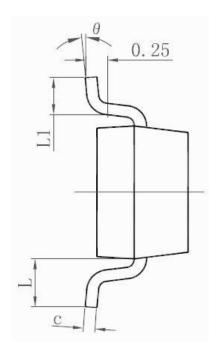
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

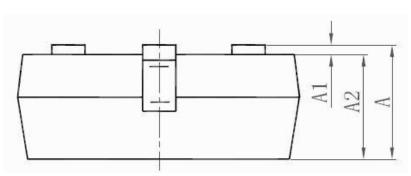




SOT-23(长电)







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP.		0.037 TYP.		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF.		0.022 REF.		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	



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